From substrates to device integration: European Innovation

Dr. Ionut RADU - Director, R&D

Heterogeneous Technology Alliance April 24, 2018





Agenda

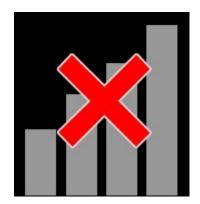
Industry challenges & opportunities Value of substrate engineering 2 **RF-SOI** 3 FD-SOI Take aways 5 scitec

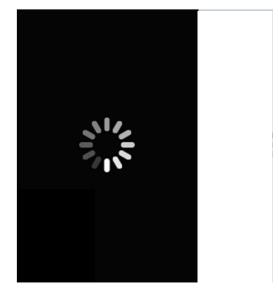
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Challenges Opportunities for semiconductor innovation



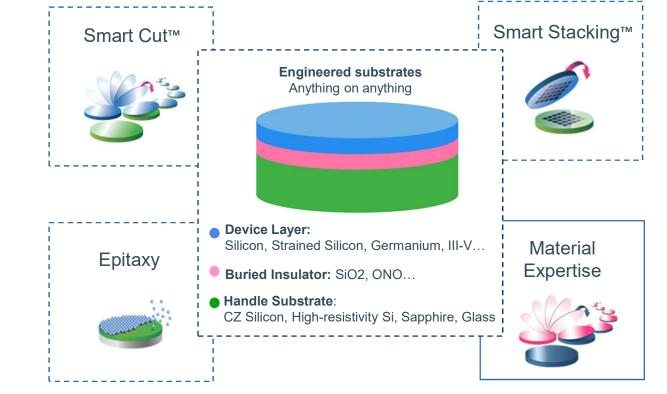




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Device performance differentiation through engineered substrates



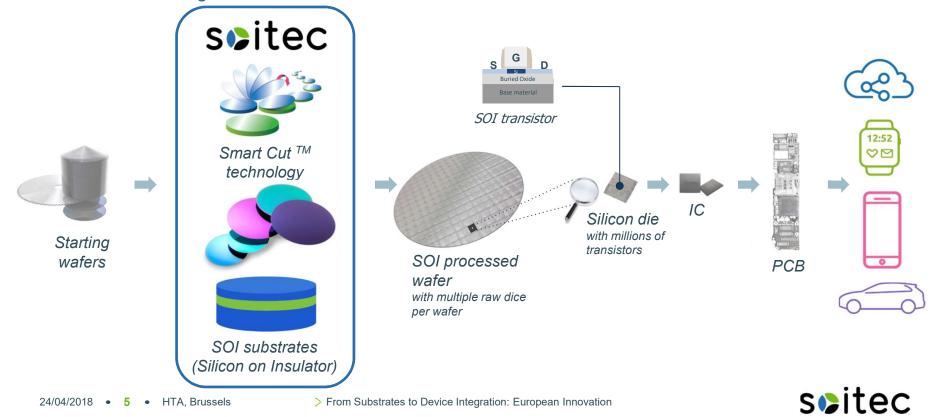




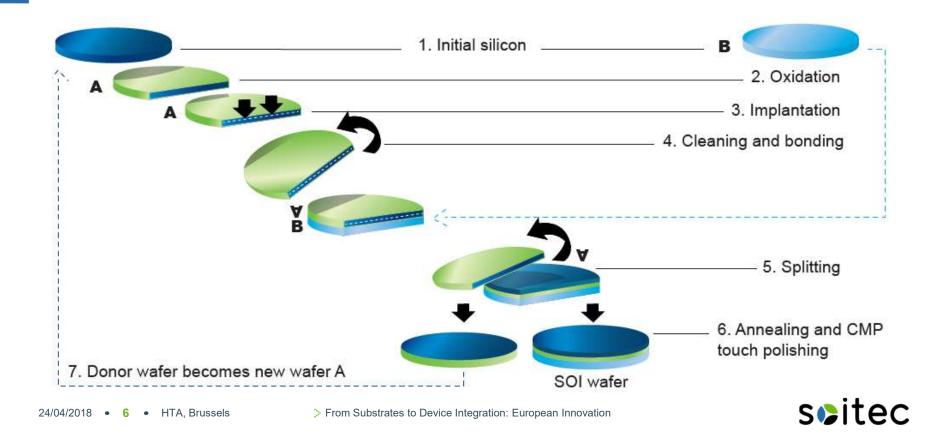


Soitec in the value chain

Engineered substrates



Smart Cut[™]: Revolutionary Technology



SOI adoption via Partnerships and Collaborations: From early R&D and technology development to manufacturing





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Contribution of many organizations and companies

But

French and EU institutions, RTO and Companies had and have the lead

National and European Funding made this possible

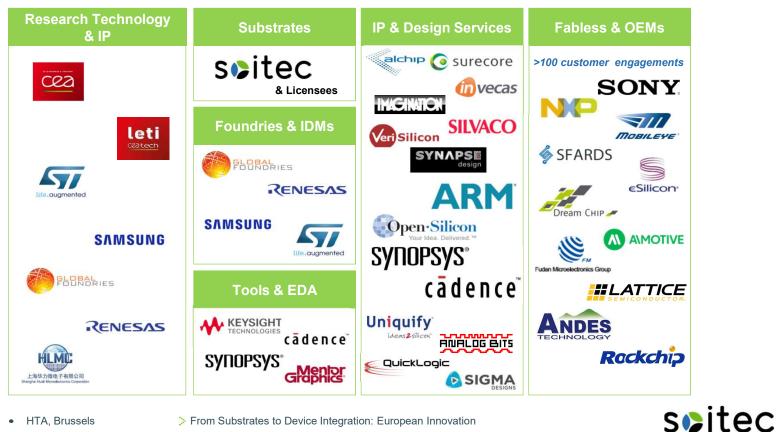
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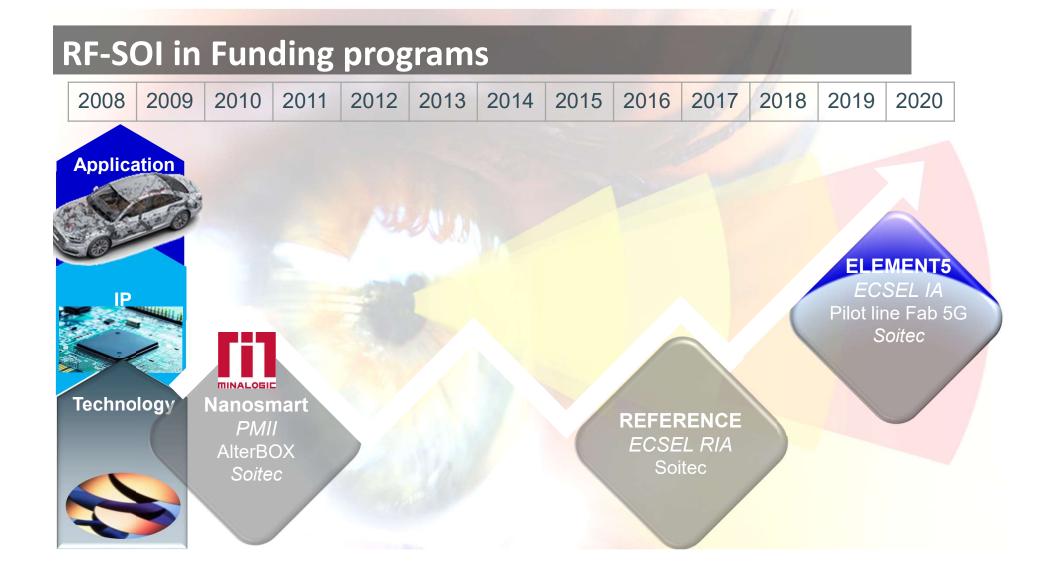
FD-SOI in Funding programs

2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020
Applica	tion				~							
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IP FDSOI 28nm ST OCEAN12												
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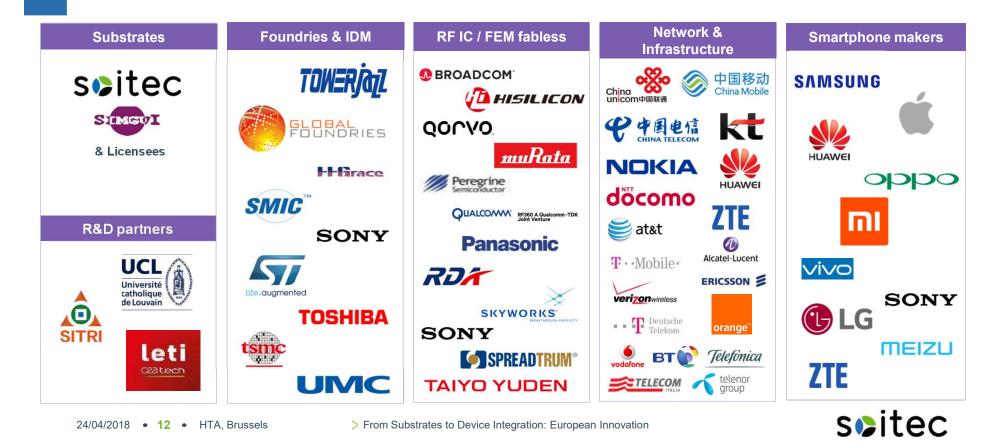
A complete FD-SOI ecosystem in motion







RF-SOI: a standard supported by a complete ecosystem



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SEMI Europe Award 2017: RF-SOI substrate technology



Bernard ASPAR, EVP Communication & Power Business Unit at Soitec Jean-Pierre RASKIN, Professor and President of Electrical Engineering Department at the Université catholique de Louvain (UCL) **Soitec** and the **Université Catholique de Louvain** (UCL) received the 2017 European SEMI Award recognizing their seminal work with radio frequency silicon-on-insulator (RF-SOI) substrates at the SEMI Industry Strategy Symposium (ISS Europe 2018) in Dublin on March 6th 2018

This award is a great recognition of Soitec's efforts to industrialize RF-SOI and make it an industry standard

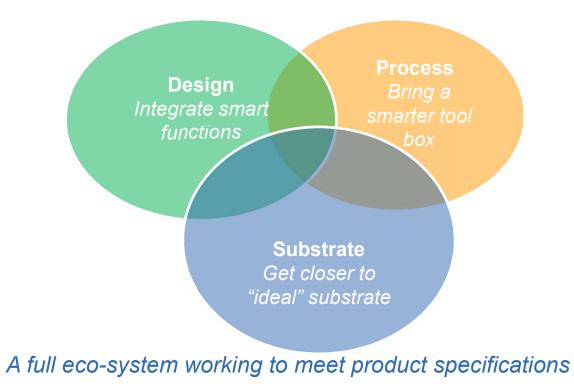
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Co-optimization from early R&D phase



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Takeaway

Engineered Substrates represent foundation of advanced electronic circuits

Soitec's technology roadmap will continue to enable next generation of devices

System Design-Technology-Substrate Co-Optimization is required to establish technology standards: collaborative R&D

Smart Things Opportunity ahead: 5G, IoT, Automotive, Health & Medical

HTA - 10th year anniversary

Brussels, 24 April 2018



Sourcing value from substrate: learn from the nature

